

Mezalok HSLF

TE Internal #: 2355827-2

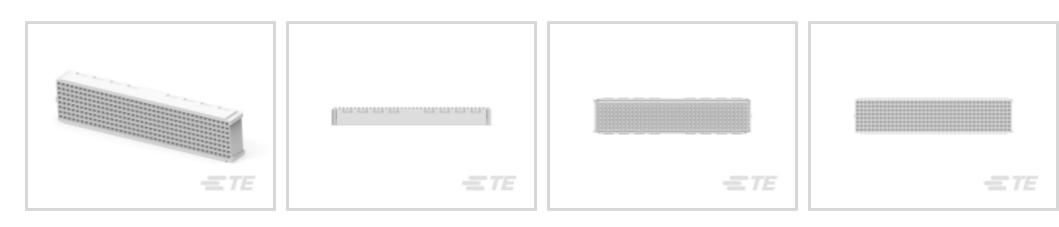
PCB Mount Receptacle, Vertical, Board-to-Board, 320 Position, 1.27 mm [.05 in] Centerline, Gold, Surface Mount - Solder Ball, Signal,

Mezalok HSLF

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 320

Number of Rows: 8

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
PCB Mount Orientation	Vertical
Number of Positions	320
Number of Rows	8
Board-to-Board Configuration	Parallel
Body Features	
Primary Product Color	Natural
Contact Features	
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	50 μm[50 μin]
Contact Type	Socket

1.5 A

Contact Current Rating (Max)



Termination Method to Printed Circuit Board	Surface Mount - Solder Ball
Mechanical Attachment	
Mating Alignment	With
Mating Alignment Type	Keyed
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP
Dimensions	
Row-to-Row Spacing	1.27 mm[.05 in]
Stack Height	10 mm[.394 in]
Usage Conditions	
Operating Temperature Range	-55 – 125 °C[-67 – 257 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tape & Reel

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
Halogen Content	Not Yet Reviewed for halogen content



Solder Process Capability

Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Mezalok HSLF



Customers Also Bought









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Documents

Product Drawings

Mezalok, LF SKT, 320 p, 10 mm, 50 Au, LF

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2355827-2_2.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2355827-2_2.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2355827-2_2.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Product Specification

English

Product Specification

English